

IN THE CLAIMS:

**Please cancel claim 56 without prejudice, and please amend claim 50, 54, 55, 57, 58, and 59 as shown below. The status of all claims is summarized as follows:**

Claims 1-49 (previously cancelled)

50. (Currently Amended) Electrical connection between two electronic components, comprising:  
a conductive path consisting essentially of a metallic coating having at least one electrically-conductive layer, said metallic coating disposed on an elongate member, said coating extending between and interconnecting two electronic components, wherein said elongate member comprises a first material, and said metallic coating comprises a second material that is more resilient than said first material.
51. Electrical connection, according to claim 50, wherein:  
the coating is a plating having at least one layer.
52. Electrical connection, according to claim 50, wherein:  
the elongate member is a wire.
53. Electrical connection, according to claim 52, wherein:  
the wire is electrically conductive.
54. (Currently Amended) Electrical connection, according to claim 52, wherein:  
the wire is selected from a group ~~consisting of~~ comprising gold and its alloys.
55. (Currently Amended) Electrical connection, according to claim 52, wherein:  
the wire is selected from a group ~~consisting of~~ comprising aluminum, copper, metals of the platinum group, lead, tin, indium, and their alloys;

Claim 56 (canceled)

57. (Currently Amended) Electrical connection, according to claim 50, wherein:

the plating is a material selected from the group ~~consisting of~~ comprising nickel and its alloys.

58. (Currently Amended) Electrical connection, according to claim 50, wherein:

the plating is a material selected from the group ~~consisting of~~ comprising copper, cobalt, iron, nickel, and their alloys, ~~and Ni/Fe/Co materials.~~

59. (Currently Amended) Electrical connection, according to claim 50, wherein:

the plating is a material selected from the group ~~consisting of~~ comprising gold, silver, elements of the platinum group, noble or semi-noble metals and their alloys, tungsten, molybdenum, cobalt, zinc, tin, solder, and copper.

Claims 60-324 (previously cancelled)

325. Interposer, comprising:

a dielectric substrate having a first surface and a second surface opposite the first surface, a first plurality of conductive areas on the first surface, a second plurality of conductive areas on the second surface, each of the first plurality of conductive areas electrically connected to a corresponding one of the second conductive areas;

a first plurality of resilient contact structures extending from the first conductive areas; and  
a second plurality of contact structures extending from the first conductive areas.

326. Interposer, according to claim 325, wherein:

the first plurality of resilient contact structures are compliant contact structures.

327. Interposer, according to claim 326, further comprising:

at least one standoff element fabricated on the first surface, to limit deflection of the first plurality of resilient contact structures.

328. Interposer structure, according to claim 325, wherein:  
the electrical connections between the first plurality of conductive areas and the second plurality of conductive areas is plated through holes.
329. Interposer, according to claim 325, wherein:  
the second plurality of contact structures are resilient contact structures.
330. Interposer, according to claim 329, wherein:  
the second plurality of contact structures are non-resilient contact structures.
331. Interposer, according to claim 325, wherein:  
at least one of either of the first plurality of resilient contact structures and the second plurality of contact structures comprises at least two contact structures.
332. Interposer, comprising:  
a dielectric substrate having a first surface and a second surface opposite the first surface, and having a plurality of conductive areas on the first surface;  
a plurality of resilient contact structures mounted to the plurality of conductive areas, and having a first portion extending beyond the first surface of the dielectric substrate for making a connection to a first electronic component, and having a second portion contiguous with the first portion and extending beyond the second surface of the dielectric substrate for making an interconnect to a second electronic component.
333. Interposer, according to claim 332, wherein:  
the second portions of the plurality of resilient contact structures extend through holes in the substrate.
334. Interposer, according to claim 325, wherein:  
the second plurality of contact structures are resilient contact structures; and  
further comprising:  
conductive traces on both surfaces of the dielectric substrate.

335. Interposer, according to claim 325, further comprising:  
standoff elements on the first side of the substrate
336. Interposer, according to claim 325, further comprising:  
a plurality of conductive areas on the first side of the substrate;  
wherein:  
the first plurality of resilient contact structures extend from the conductive areas.
337. Interposer, according to claim 336, further comprising:  
a plurality of holes extending through the substrate; and  
wherein:  
the second contact structures extend from the conductive areas through the plurality of  
holes, to the second side of the substrate.
338. Interposer, according to claim 325, wherein:  
the first plurality of resilient contact structures are arranged in pairs.
339. Interposer, according to claim 325, further comprising:  
a plurality of conductive areas on the first side of the substrate; and  
a plurality of holes extending through the substrate;  
wherein:  
the first plurality of resilient contact structures extend through the plurality of holes beyond  
the first side of the substrate to beyond the second side of the substrate; and  
the first plurality of resilient contact structures are electrically connected to the conductive  
areas.

340. Interposer, comprising:  
a substrate having a plurality of holes extending from a first surface of the substrate to a second surface of the substrate;  
a plurality of contact structures, each contact structure disposed within a corresponding hole;  
and  
means for supporting the contact structures within the holes.
341. Interposer, according to claim 340, wherein:  
the contact structures are resilient contact structures.
342. Interposer, according to claim 340, wherein:  
the means for supporting is an elastomeric material.
343. Interposer, according to claim 342, wherein:  
at least a portion of the elastomeric material is electrically conductive.
344. Interposer, according to claim 340, further comprising:  
a metallic surface within each hole; and  
wherein:  
the means for supporting is solder.
345. Interposer, according to claim 340, wherein:  
the substrate is metallic, and is overcoated with an insulating material.

Claims 346-374 (previously cancelled)